

Claims listing:

1. (Currently amended) A cooler for cooling of electronic components comprising at least two heatsinks thermally connected with each other by heat spreading means, and ~~at least one~~ a double inlet centrifugal blower comprising a casing with two inlets and an outlet, ~~[[an]]~~ a radial impeller with an axle and an electric drive, said cooler is thermally connected with said electronic component, wherein

(i) each of said heatsinks ~~comprises~~ comprising inflow and outflow openings, and thermally connected heat exchanging means and a base;

(ii) said impeller comprising radial blades located from both sides of an impeller disk;

(iii) said double inlet centrifugal blower ~~[[is]]~~ being located between said heatsinks thus each of said outflow openings is coincided with said closest inlet, so cooling air flows through said inflow openings, said heat exchanging means, said outflow openings and said inlets of said blower in a series way.

2. (Canceled).

3. (Original) The cooler as in claim 1, wherein said heat spreading means are made as at least one heat pipe comprising evaporator and condenser parts that thermally connected with said bases of two different heatsinks.

4. (Original) The cooler as in claim 1, wherein said heat spreading means are made as a high heat conductive plate located from one side of and perpendicularly to said bases.

5. (Canceled).

6. (Original) The cooler as in claim 4, wherein said heatsinks and said high heat conductive plate made as a single whole.

7. (Original) The cooler as in claim 1, wherein said heat exchanging means are upstanding pins and/or fins contacting said base.